

FULL WAFER CONTACTER AND APPLICATIONS THEREOF

ABSTRACT OF THE DISCLOSURE

A replacement for probe cards includes a full wafer contacter. A first surface of the full wafer contacter is brought into contact with, and the contacter is attached to, a wafer, thereby making electrical connection with at least a portion of the contact pads on each of a plurality of integrated circuits on the wafer. The full wafer contacter provides conductive pathways from the IC contact pads to a second surface of the full wafer contacter where a corresponding set of contact pads provide access to test systems and/or other devices. The contact pads on the second surface of the full wafer contacter are typically larger than the contact pads of the integrated circuits, and are typically spaced farther apart from each other. The full wafer contacter is constructed to be suitable to provide access to the contact pads of the unsingulated integrated circuits during a wafer burn-in process.